

PS7342C-1A, PS7342CL-1A**CURRENT LIMIT TYPE
6-PIN DIP OCMOS FET
(1-ch OCMOS FET)****DESCRIPTION**

The PS7342C-1A and PS7342CL-1A are solid state relays containing a GaAs LED on the light emitting side (input side) and MOS FETs and current control circuit on the output side.

They are suitable for analog signal control because of their low offset and high linearity.

The PS7342CL-1A has a surface mount type lead.

FEATURES

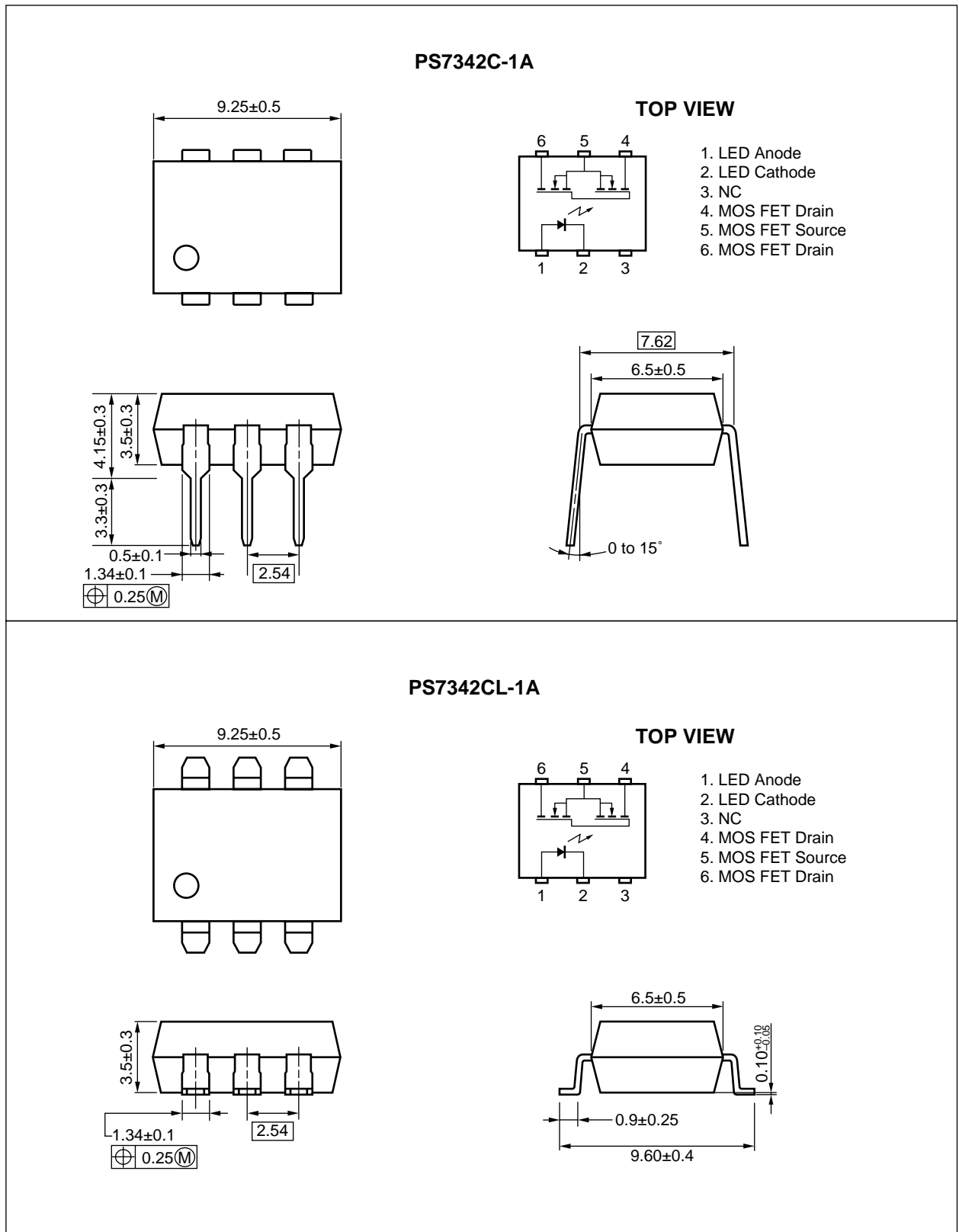
- Limit current ($I_{LMT} = 175$ to 370 mA)
- High isolation voltage ($BV = 3\ 750$ V r.m.s.)
- 1 channel type (1 a output)
- Designed for AC/DC switching line changer
- Small package (6-pin DIP)
- Low offset voltage
- PS7342CL-1A: Surface mount type

APPLICATIONS

- Exchange equipment
- Measurement equipment
- FA/OA equipment

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Not all devices/types available in every country. Please check with local NEC representative for availability and additional information.

★ PACKAGE DIMENSIONS (in millimeters)



PS7342CL-1A

ABSOLUTE MAXIMUM RATINGS (T_A = 25 °C, unless otherwise specified)

Parameter		Symbol	Ratings	Unit
Diode	Forward Current (DC)	I _F	50	mA
	Reverse Voltage	V _R	5.0	V
	Power Dissipation	P _D	50	mW
	Peak Forward Current ^{*1}	I _{FP}	1	A
MOS FET	Break Down Voltage	V _L	400	V
	Continuous Load Current	I _L	170	mA
	Power Dissipation	P _D	560	mW
Isolation Voltage ^{*2}		BV	3 750	Vr.m.s.
Total Power Dissipation		P _T	610	mW
Operating Ambient Temperature		T _A	-40 to +85	°C
Storage Temperature		T _{stg}	-40 to +125	°C

*1 PW = 100 μs, Duty Cycle = 1 %

*2 AC voltage for 1 minute at T_A = 25 °C, RH = 60 % between input and output

RECOMMENDED OPERATING CONDITIONS (T_A = 25 °C)

Parameter	Symbol	MIN.	TYP.	MAX.	Unit
LED Operating Current	I _F	2	10	20	mA
LED Off Voltage	V _F	0		0.5	V

ELECTRICAL CHARACTERISTICS (T_A = 25 °C)

Parameter		Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Diode	Forward Voltage	V _F	I _F = 10 mA		1.2	1.4	V
	Reverse Current	I _R	V _R = 5 V			5.0	μA
MOS FET	Off-state Leakage Current	I _{Loff}	V _D = 400 V		0.001	1.0	μA
	Output Capacitance	C _{out}	V _D = 0 V, f = 1 MHz		237		pF
Coupled	On-state Resistance	R _{on1}	I _F = 10 mA, I _L = 10 mA		12	20	Ω
		R _{on2}	I _F = 10 mA, I _L = 170 mA		12	20	
	Turn-on Time	t _{on}	I _F = 10 mA, V _L = 5 V, R _L = 500 Ω,		2.0	5.0	ms
	Turn-off Time	t _{off}	PW ≥ 10 ms		0.06	1.0	
	Isolation Resistance	R _{I-O}	V _{I-O} = 1.0 kV _{DC}	10 ⁹			Ω
	Isolation Capacitance	C _{I-O}	V = 0 V, f = 1 MHz		1.1		pF
	Limit Current ^{*1}	I _{LMT}	I _F = 10 mA, t = 5 ms, V _L = 6 V	175	270	370	mA

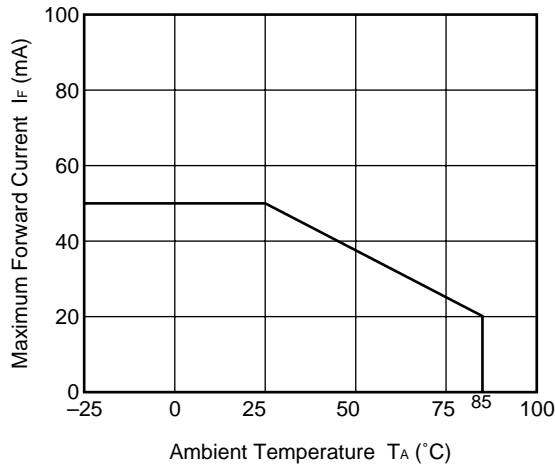
*1 N rank : 175 to 370 mA

M rank : 175 to 250 mA

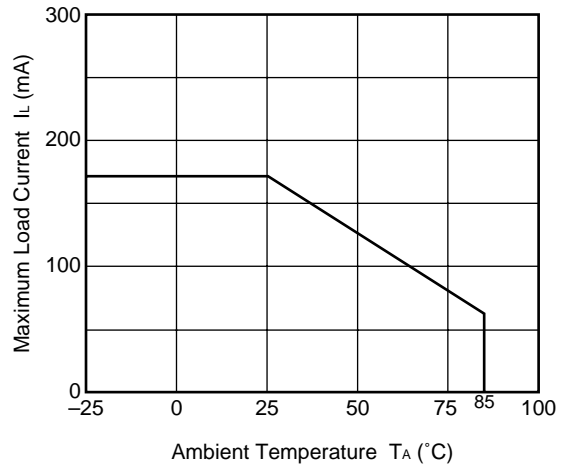
L rank : 230 to 370 mA

TYPICAL CHARACTERISTICS ($T_A = 25\text{ }^\circ\text{C}$, unless otherwise specified)

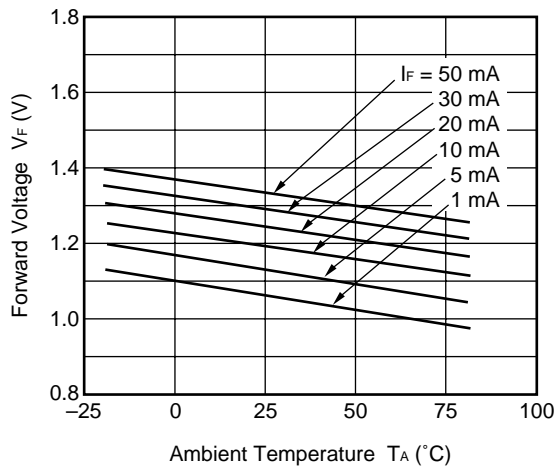
MAXIMUM FORWARD CURRENT vs. AMBIENT TEMPERATURE



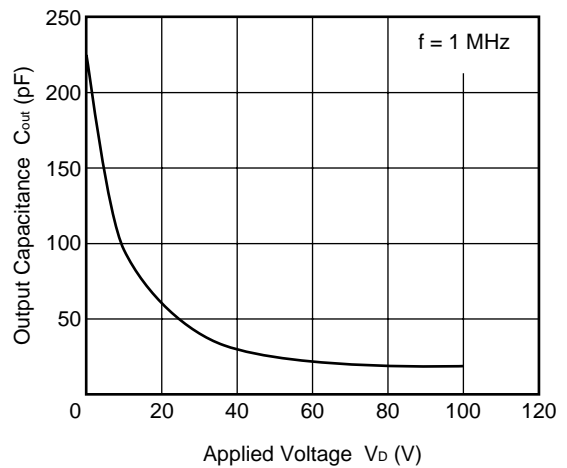
MAXIMUM LOAD CURRENT vs. AMBIENT TEMPERATURE



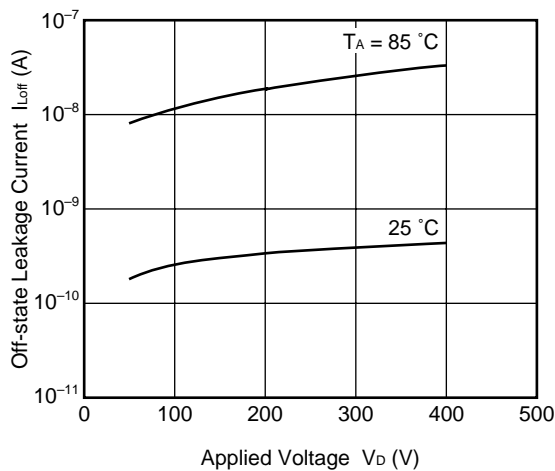
FORWARD VOLTAGE vs. AMBIENT TEMPERATURE



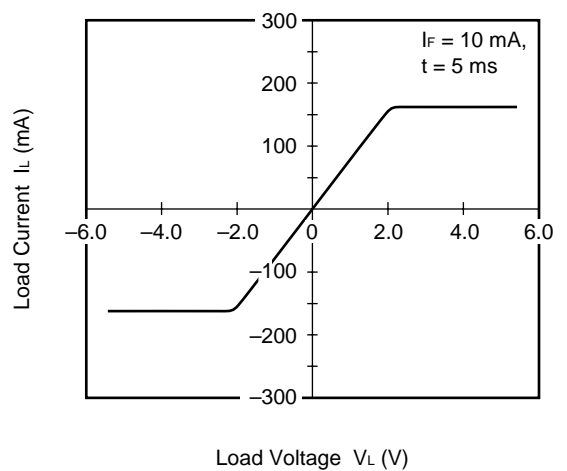
OUTPUT CAPACITANCE vs. APPLIED VOLTAGE



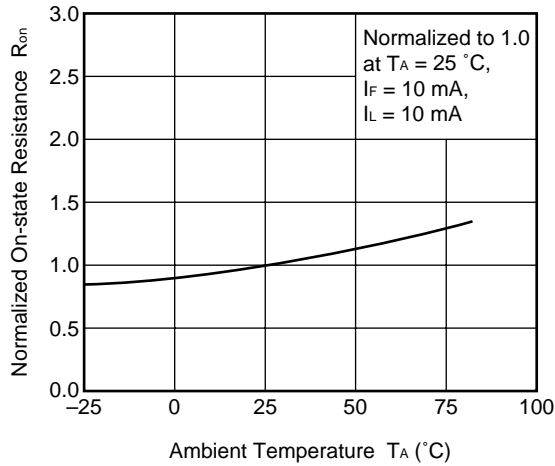
OFF-STATE LEAKAGE CURRENT vs. APPLIED VOLTAGE



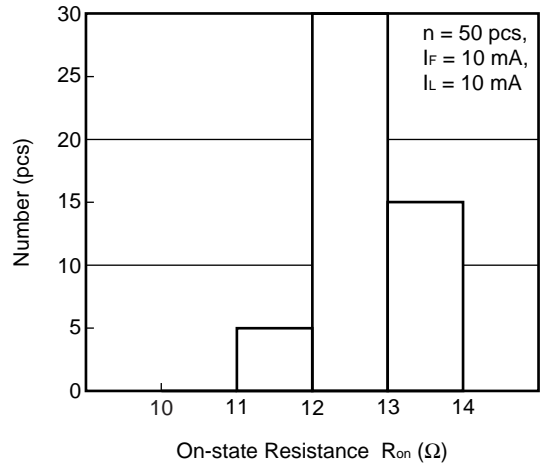
LOAD CURRENT vs. LOAD VOLTAGE



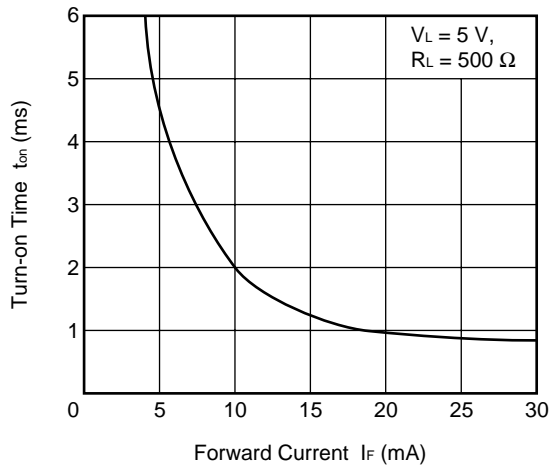
NORMALIZED ON-STATE RESISTANCE vs. AMBIENT TEMPERATURE



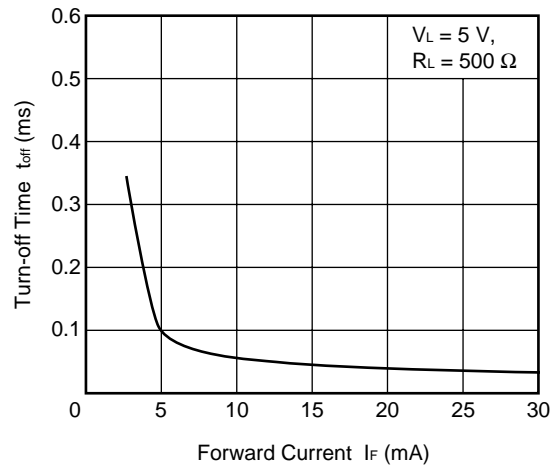
ON-STATE RESISTANCE DISTRIBUTION



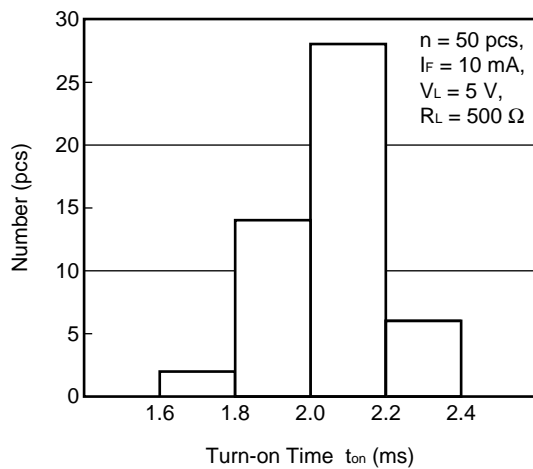
TURN-ON TIME vs. FORWARD CURRENT



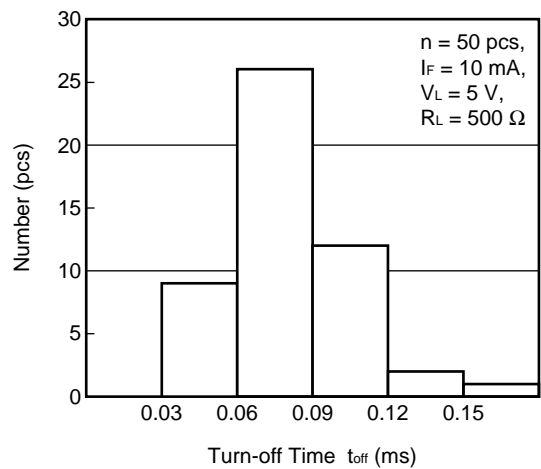
TURN-OFF TIME vs. FORWARD CURRENT



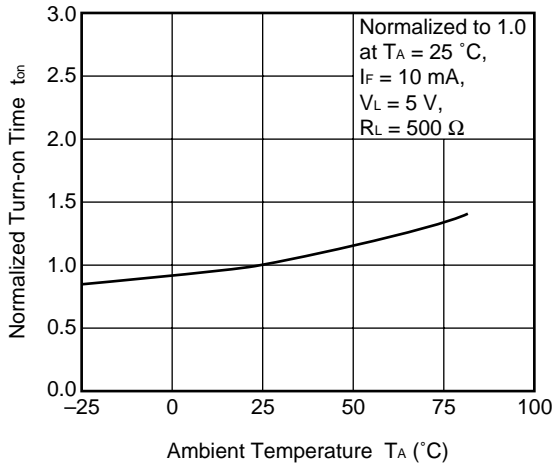
TURN-ON TIME DISTRIBUTION



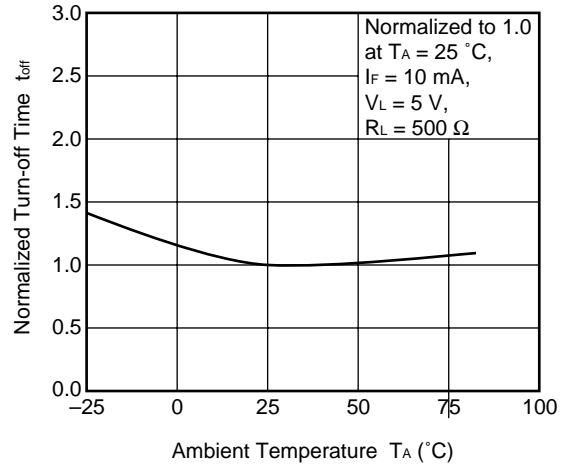
TURN-OFF TIME DISTRIBUTION



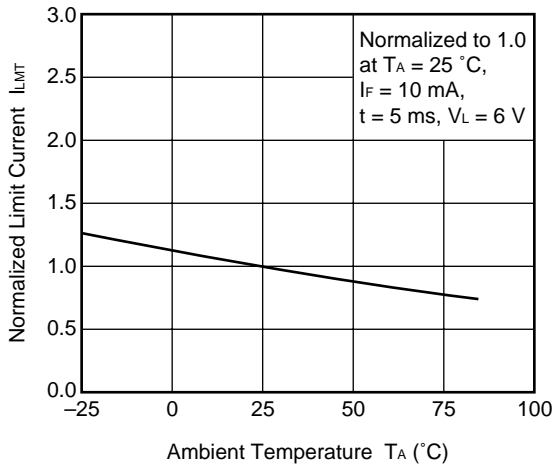
NORMALIZED TURN-ON TIME vs. AMBIENT TEMPERATURE



NORMALIZED TURN-OFF TIME vs. AMBIENT TEMPERATURE



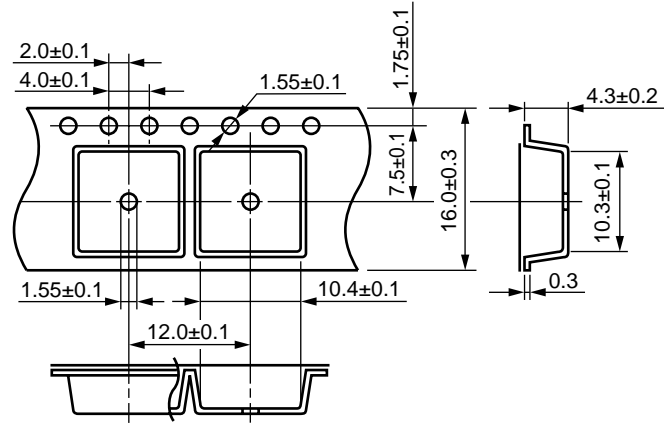
NORMALIZED LIMIT CURRENT vs. AMBIENT TEMPERATURE



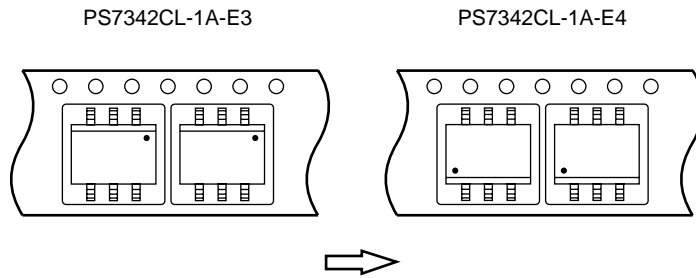
Remark The graphs indicate nominal characteristics.

TAPING SPECIFICATIONS (in millimeters)

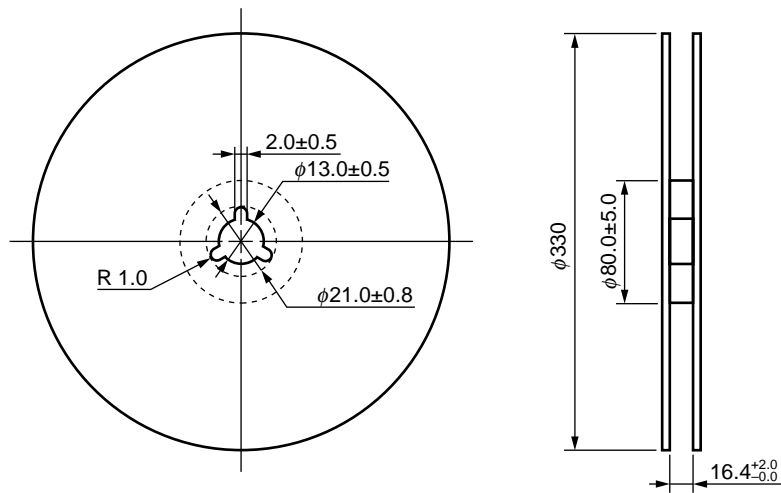
Outline and Dimensions (Tape)



Tape Direction



Outline and Dimensions (Reel)



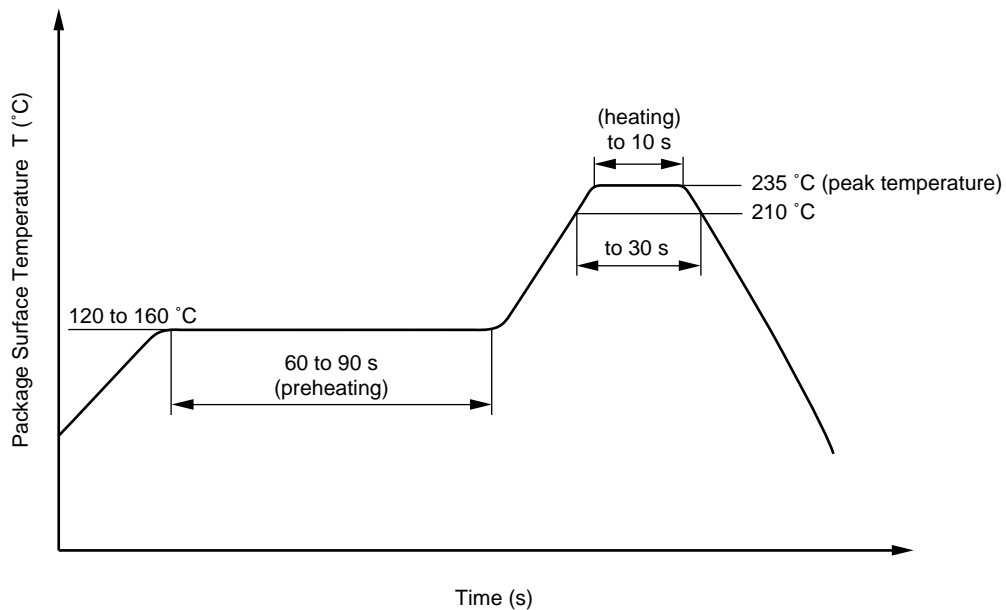
Packing: 1 000 pcs/reel

★ **RECOMMENDED SOLDERING CONDITIONS**

(1) Infrared reflow soldering

- Peak reflow temperature 235 °C (package surface temperature)
- Time of temperature higher than 210 °C 30 seconds or less
- Number of reflows One
- Flux Rosin flux containing small amount of chlorine (The flux with a maximum chlorine content of 0.2 Wt % is recommended.)

Recommended Temperature Profile of Infrared Reflow



(2) Dip soldering

- Temperature 260 °C or below (molten solder temperature)
- Time 10 seconds or less
- Number of times One
- Flux Rosin flux containing small amount of chlorine (The flux with a maximum chlorine content of 0.2 Wt % is recommended.)

(3) Cautions

- Fluxes
Avoid removing the residual flux with freon-based and chlorine-based cleaning solvent.
- Products in dry pack
After opening the dry pack, solder the products within the valid storage period specified on the label on the dry pack.

[MEMO]

[MEMO]

[MEMO]

CAUTION

Within this device there exists GaAs (Gallium Arsenide) material which is a harmful substance if ingested. Please do not under any circumstances break the hermetic seal.

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